

- NOTES:
- MATERIAL:
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
TERMINAL - COPPER ALLOY
 - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
 - PRODUCT SPECIFICATION: PS-78315-001
 - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
 - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
 - MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
DATE CODE SHOULD BE INDICATE AS YYDDDX. 'X' WILL BE THE DIE NO.
 - MODULE SEATING PLANE FROM TOP OF PCB
 - KEEP OUT ZONE RESERVED FOR LATCH

| | |
|-------------------|------------|
| UPT D/C W DIE NO | 2015/01/20 |
| EC NO: S2016-1099 | 2016/07/19 |
| DRW:NCCTEH | 2016/07/19 |
| CHKD:CGTAN | 2016/07/22 |
| APPR:SHLENI | |

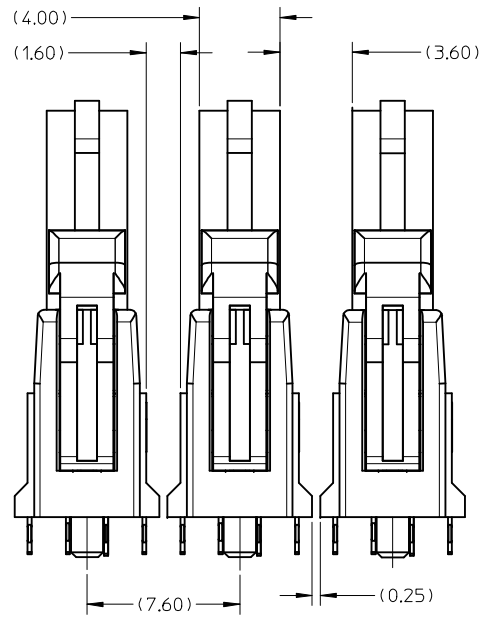
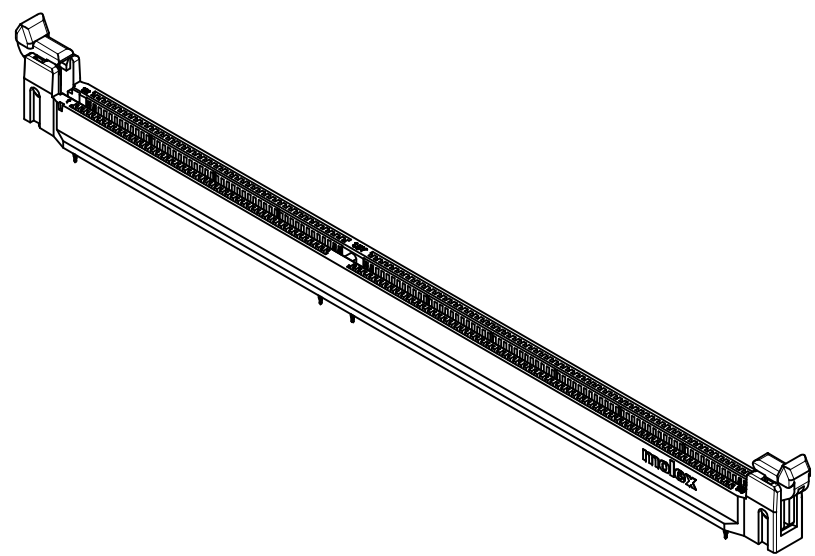
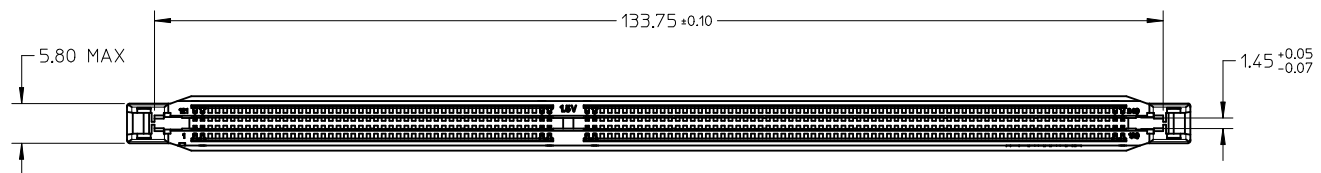
| QUALITY SYMBOLS | DESCRIPTION |
|-----------------|-------------|
| $F_A=0$ | |
| $F_G=0$ | |
| $F_B=0$ | |

| GENERAL TOLERANCES (UNLESS SPECIFIED) | |
|--|--------------|
| | mm INCH |
| 4 PLACES | ± --- ± --- |
| 3 PLACES | ± --- ± --- |
| 2 PLACES | ± 0.20 ± --- |
| 1 PLACE | ± --- ± --- |
| 0 PLACE | ± --- ± --- |
| ANGULAR ± 1 ° | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | |

| DIMENSION STYLE | |
|-----------------|------------|
| MM ONLY | |
| DRAWN BY | DATE |
| CMTEO | 2008/07/17 |
| CHECKED BY | DATE |
| CCTEH | 2008/07/30 |
| APPROVED BY | DATE |
| SHLENI | 2010/12/15 |
| MATERIAL NO. | |
| SEE TABLE | |

| | | |
|---|--------------|------------------------|
| SCALE | DESIGN UNITS | THIRD ANGLE PROJECTION |
| NTS | METRIC | |
| TITLE | | |
| DDR3 DIMM (LSP, VLP) 100MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | | |
| molex | | |
| DOCUMENT NO. | SHEET NO. | |
| SD-78315-001 | 1 OF 6 | |
| THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | |

10 9 8 7 6 5 4 3 2 1



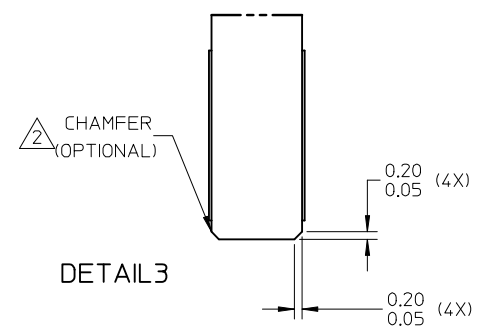
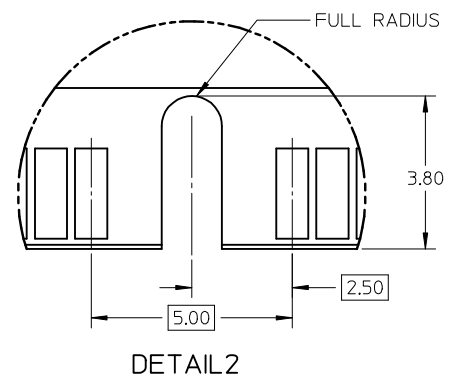
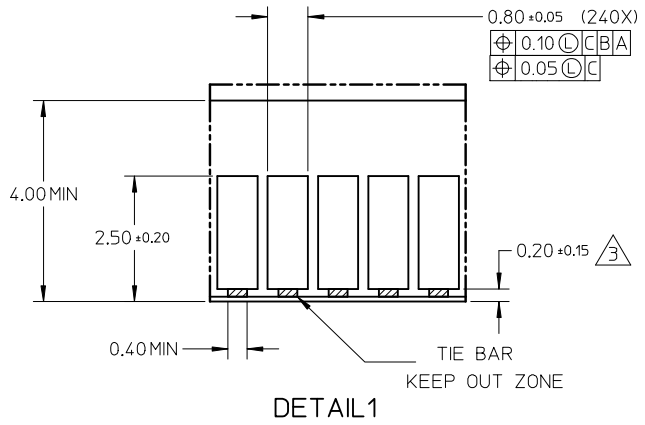
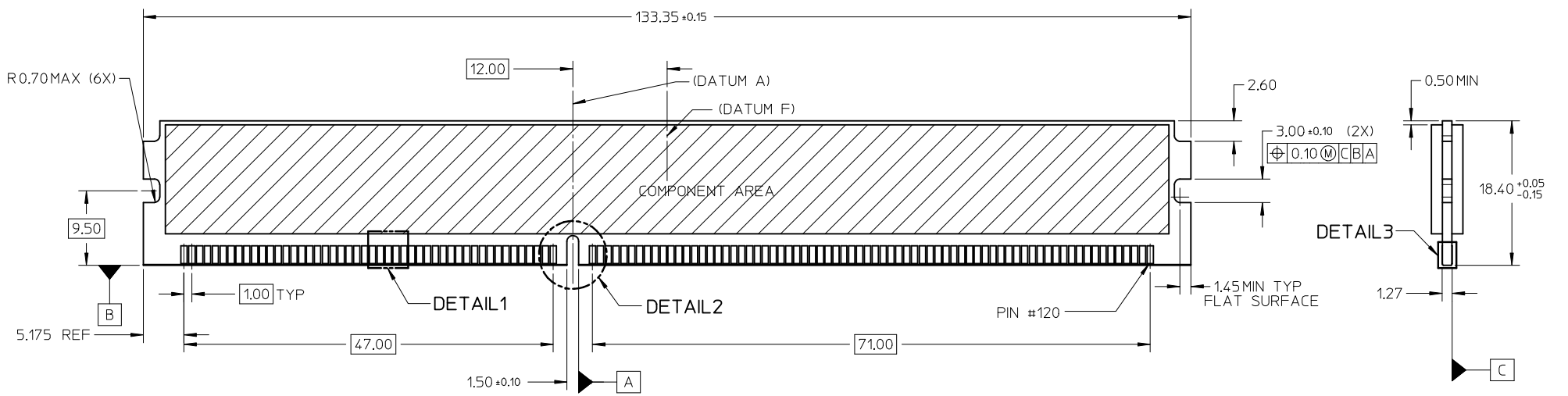
MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

| | | | | | | | | | | |
|--|--|---------------------------------------|------------|---|------------|------------------------|------------------------|------------------------|-----------|--|
| UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22 | QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$ | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE NTS | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | mm | INCH | DRAWN BY | DATE | TITLE | | | | |
| | | 4 PLACES ± --- | ± --- | CMTEO | 2008/07/17 | DDR3 DIMM (LSP, VLP) | | | | |
| | | 3 PLACES ± --- | ± --- | CHECKED BY | DATE | 1.00MM PITCH, 240 CKTS | | | | |
| 2 PLACES ± 0.20 | ± --- | APPROVED BY | DATE | VERTICAL P/F, LOWLLCR | | | | | | |
| 1 PLACE ± --- | ± --- | SHLENI | 2010/12/15 | MATERIAL NO. | | DOCUMENT NO. | | | SHEET NO. | |
| 0 PLACE ± --- | ± --- | ANGULAR ± 1 ° | | SEE TABLE | | SD-78315-001 | | | 2 OF 6 | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | |

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

009MODULE CARD
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



NOTES:

1. RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
 OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
 OVER 2.00 MICROMETERS NICKEL MUST
 USE AN ELECTRONIC CONTACT GRADE
 CORROSIVE BARRIER LUBRICANT

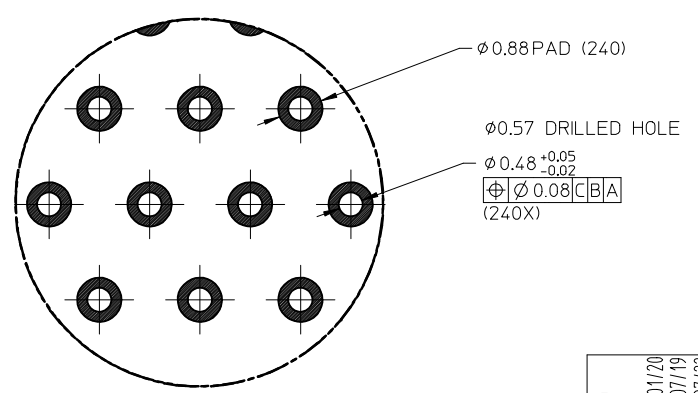
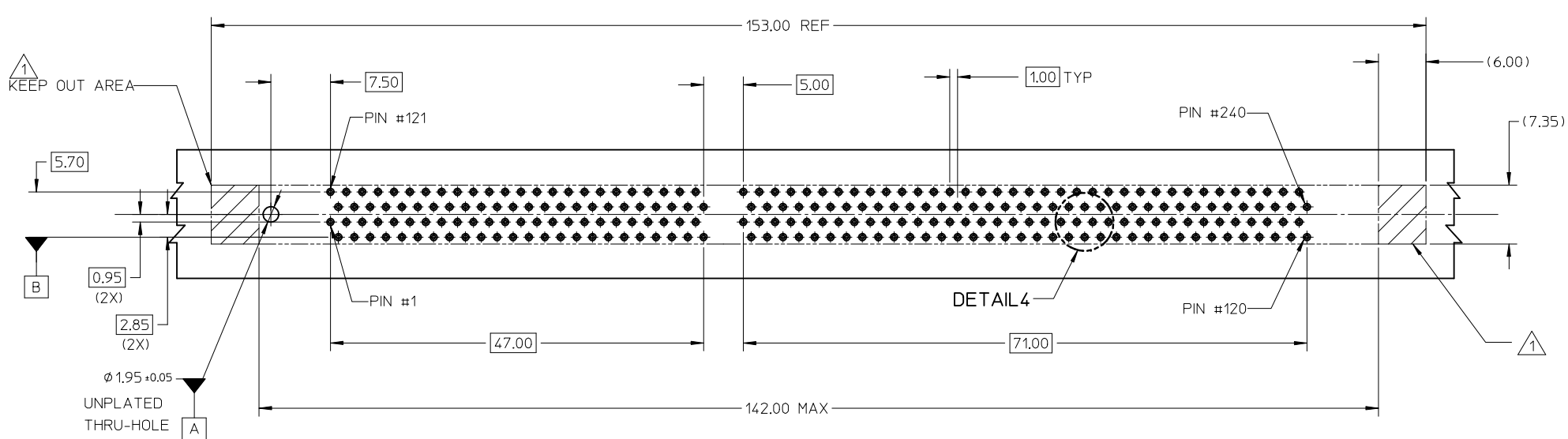
2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS

3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

| | | | | | | | | | | |
|--|--|---|------------|-----------------------------------|------------|------------------------|-------------------------------|------------------------|--|--|
| UPT D/C W DIE NO EC NO: S2016-1099 DRW: CCTEH CHKD: CGTAN APPR: SHLENI 2015/01/20 2016/07/19 2016/07/22 | QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$ | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE NTS | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | mm | INCH | DRAWN BY | DATE | TITLE | | | | |
| | | 4 PLACES ± --- | ± --- | CMTEO | 2008/07/17 | DDR3 DIMM (LSP, VLP) | | | | |
| | | 3 PLACES ± --- | ± --- | CCTEH | 2008/07/30 | 1.00MM PITCH, 240 CKTS | | | | |
| 2 PLACES ± 0.20 | ± --- | SHLENI | 2010/12/15 | VERTICAL P/F, LOWLLCR | | | | | | |
| 1 PLACE ± --- | ± --- | MATERIAL NO. | | SEE TABLE | | DOCUMENT NO. | | SHEET NO. | | |
| 0 PLACE ± --- | ± --- | ANGULAR ± 1 ° | | SIZE | | SD-78315-001 | | 3 OF 6 | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | | |

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



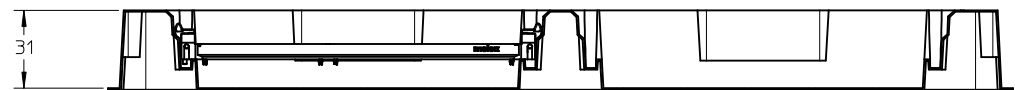
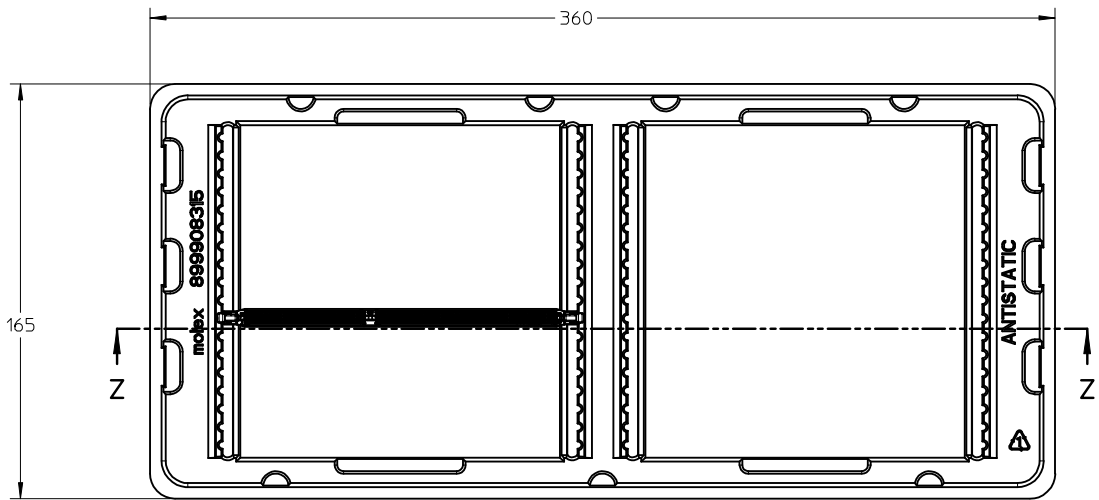
NOTES:
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

| | | | | | | | | | | |
|--|--|---------------------------------------|----------------------------|---|----------------------------|--|------------------------------|---------------------|-----------------------|--------------------|
| UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHYK: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22 | QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$ | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE NTS | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | | |
| | | | mm INCH | DRAWN BY CMTEO | DATE 2008/07/17 | TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | | | | |
| | | 4 PLACES ± --- ± --- | 3 PLACES ± --- ± --- | 2 PLACES ± 0.20 ± --- | 1 PLACE ± --- ± --- | 0 PLACE ± --- ± --- | CHECKED BY CCTEH | DATE 2008/07/30 | APPROVED BY SHLENI | DATE 2010/12/15 |
| | | ANGULAR ± 1 ° | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | MATERIAL NO. SEE TABLE | DOCUMENT NO. SD-78315-001 | SHEET NO. 4 OF 6 | | |

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z

NOTE:
1. NO. OF CAVITY - 18 X 2 =36

| | | | | | | | | | |
|--|---|---|----------------------|--|---------------------|---------------------------|------------------------------|---------------------|--|
| UPT D/C W DIE NO EC NO: S2016-1099 DRW: CCTEH CHKD: CGTAN APPR: SHLENI 2015/01/20 2016/07/19 2016/07/22 | QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_G = 0$ $\nabla_F = 0$ | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | SCALE NTS | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | 4 PLACES ± --- ± --- | 3 PLACES ± --- ± --- | 2 PLACES ± 0.20 ± --- | 1 PLACE ± --- ± --- | 0 PLACE ± --- ± --- | DRAWN BY CMTEO | DATE 2008/07/17 | TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR |
| | | ANGULAR ± 1 ° | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | MATERIAL NO. SEE TABLE | DOCUMENT NO. SD-78315-001 | SHEET NO. 5 OF 6 | |
| | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | |

9 8 7 6 5 4 3 2 1

| PART NO. | KEY POS. | DIM 'P' | RECOMMENDED PCB THICKNESS | PLATING OPTION | | LATCH COLOUR | HOUSING COLOUR |
|------------|---------------|---------|---------------------------|--|--|--------------|----------------|
| | | | | CONTACT AREA | TAIL AREA | | |
| 78315-0001 | CENTER (1.5V) | 1.85 | 2.40 | 0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE | 0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE | BLACK | BLACK |
| 78315-0051 | | | | | | BLUE | BLUE |
| 78315-0011 | | 2.85 | 2.60 | | | BLACK | BLACK |

| | | | | | | | | |
|--|-----------------|--|--------|-----------------|---|--------------|---|--|
| UPT D/C W DIE NO EC NO: S2016-1099 DRWN: CCTEH 2015/01/20 CHKD: CGTAN 2016/07/19 APPR: SHLENI 2016/07/22 | QUALITY SYMBOLS | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE | SCALE | DESIGN UNITS | THIRD ANGLE PROJECTION | |
| | $F_A=0$ | mm | INCH | MM ONLY | NTS | METRIC | | |
| | $F_G=0$ | 4 PLACES | ± --- | ± --- | DRAWN BY | DATE | TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | |
| | $F_P=0$ | 3 PLACES | ± --- | ± --- | CMTEO | 2008/07/17 | | |
| | | 2 PLACES | ± 0.20 | ± --- | CHECKED BY | DATE | <div style="text-align: center; font-weight: bold; font-size: 1.2em;">molex</div> DOCUMENT NO. SD-78315-001 SHEET NO. 6 OF 6 | |
| | 1 PLACE | ± --- | ± --- | DATE | 2008/07/30 | | | |
| | 0 PLACE | ± --- | ± --- | APPROVED BY | DATE | | | |
| | | ANGULAR ± 1 ° | | SHLENI | 2010/12/15 | | | |
| | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | MATERIAL NO. | SEE TABLE | | | |
| | | | | SIZE | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | |